

**Description**

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

**Features**

- $BV_{CEO} > 40V$
- $I_C = 600mA$  High Collector Current
- Epitaxial Planar Die Construction
- Ideal for Medium Power Amplification and Switching
- Ultra-Small Surface Mount Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

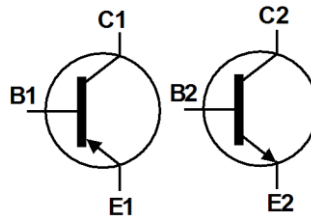
**Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Finish; Solderable per MIL-STD-202, Method 208③
- Weight: 0.006 grams (Approximate)

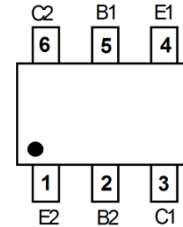
SOT363



Top View



Device Symbol



Top View  
Pin-Out

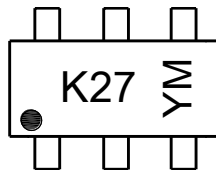
**Ordering Information** (Note 5)

Product	Compliance	Marking	Reel Size (inch)	Tape Width (mm)	Quantity per Reel
MMDT2227Q-7-F	Automotive	K27	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to <https://www.diodes.com/quality/product-compliance-definitions/>.
  5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**

SOT363



K27 = Product Type Marking Code  
 YM = Date Code Marking  
 Y or  $\bar{Y}$  = Year (ex: E = 2017)  
 M or  $\bar{M}$  = Month (ex: 9 = September)

Date Code Key

Year	2017	2018	2019	2020	2021	2022	2023	2024
Code	E	F	G	H	I	J	K	L

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Absolute Maximum Ratings, NPN (2222A Type)** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	75	V
Collector-Emitter Voltage	$V_{CEO}$	40	V
Emitter-Base Voltage	$V_{EBO}$	6	V
Collector Current	$I_C$	600	mA

**Absolute Maximum Ratings, PNP (2907A Type)** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-60	V
Collector-Emitter Voltage	$V_{CEO}$	-60	V
Emitter-Base Voltage	$V_{EBO}$	-6	V
Collector Current	$I_C$	-600	mA

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	$P_D$	200	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	625	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case (Note 7)	$R_{\theta JC}$	150	$^\circ\text{C}/\text{W}$
Operating and Storage and Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- 6. For the device mounted on minimum recommended pad layout FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  - 7. Thermal resistance from junction to the top of package.
  - 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

**Thermal Characteristic and Derating Information**

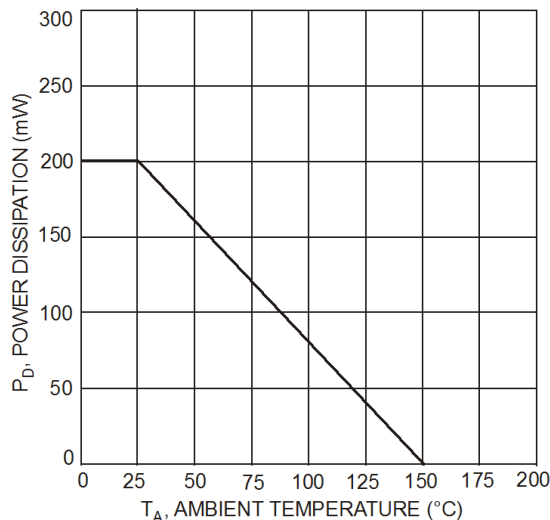


Fig. 1 Max Power Dissipation vs. Ambient Temperature

**Electrical Characteristics, NPN (2222A Type)** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>					
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	75	—	V	I <sub>C</sub> = 100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	40	—	V	I <sub>C</sub> = 10.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6.0	—	V	I <sub>E</sub> = 100μA, I <sub>C</sub> = 0
Collector-Base Cut-Off Current	I <sub>CBO</sub>	—	10	nA μA	V <sub>CB</sub> = 60V, I <sub>E</sub> = 0 V <sub>CB</sub> = 60V, I <sub>E</sub> = 0, T <sub>A</sub> = +150°C
Collector-Emitter Cut-Off Current	I <sub>CEX</sub>	—	10	nA	V <sub>CE</sub> = 60V, V <sub>EB(OFF)</sub> = 3.0V
Emitter-Base Cut-Off Current	I <sub>EBO</sub>	—	10	nA	V <sub>EB</sub> = 5.0V, I <sub>C</sub> = 0
Base Cut-Off Current	I <sub>BL</sub>	—	20	nA	V <sub>CE</sub> = 60V, V <sub>EB(OFF)</sub> = 3.0V
<b>ON CHARACTERISTICS (Note 9)</b>					
DC Current Gain	h <sub>FE</sub>	35	—	—	I <sub>C</sub> = 100μA, V <sub>CE</sub> = 10V I <sub>C</sub> = 1.0mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 150mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 500mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V, T <sub>A</sub> = -55°C I <sub>C</sub> = 150mA, V <sub>CE</sub> = 1.0V
		50	—		
		75	—		
		100	300		
		40	—		
		50	—		
35	—	—	—		
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	0.3 1.0	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.60	1.2 2.0	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	C <sub>obo</sub>	—	8	pF	V <sub>CB</sub> = 10V, f = 1.0MHz, I <sub>E</sub> = 0
Input Capacitance	C <sub>ibo</sub>	—	25	pF	V <sub>EB</sub> = 0.5V, f = 1.0MHz, I <sub>C</sub> = 0
Current Gain-Bandwidth Product	f <sub>T</sub>	300	—	MHz	V <sub>CE</sub> = 20V, I <sub>C</sub> = 20mA, f = 100MHz
Noise Figure	NF	—	4.0	dB	V <sub>CE</sub> = 10V, I <sub>C</sub> = 100μA, R <sub>S</sub> = 1.0kΩ, f = 1.0kHz
<b>SWITCHING CHARACTERISTICS</b>					
Delay Time	t <sub>D</sub>	—	10	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA, V <sub>BE(OFF)</sub> = 0.5V, I <sub>B1</sub> = 15mA
Rise Time	t <sub>R</sub>	—	25	ns	
Storage Time	t <sub>S</sub>	—	225	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA, I <sub>B1</sub> = - I <sub>B2</sub> = 15mA
Fall Time	t <sub>F</sub>	—	60	ns	

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

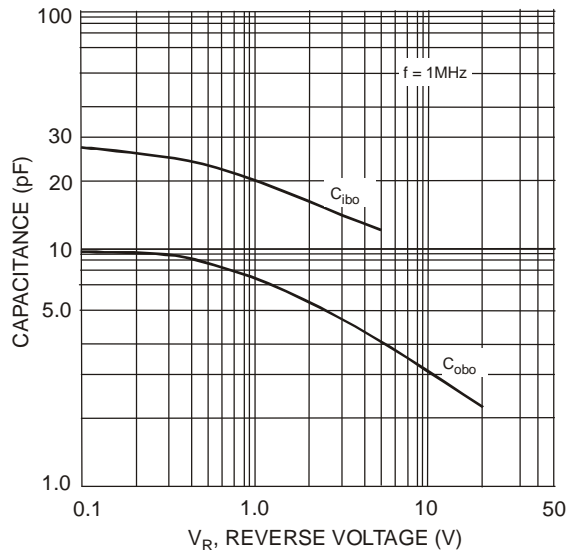


Fig. 1 (2222A) Typical Capacitance

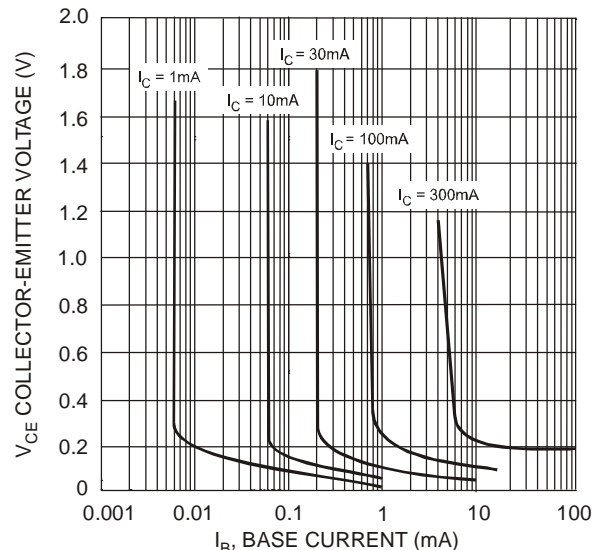


Fig. 2 Typical Collector Saturation Region (2222A Type - NPN)

**Electrical Characteristics, PNP (2907A Type) (@T<sub>A</sub> = +25°C, unless otherwise specified.)**

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 10)</b>					
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-60	—	V	I <sub>C</sub> = -100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	-60	—	V	I <sub>C</sub> = -10mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-6.0	—	V	I <sub>E</sub> = -100μA, I <sub>C</sub> = 0
Collector Cutoff Current	I <sub>CBO</sub>	—	-10	nA μA	V <sub>CB</sub> = -50V, I <sub>E</sub> = 0 V <sub>CB</sub> = -50V, I <sub>E</sub> = 0, T <sub>A</sub> = +125°C
Collector Cutoff Current	I <sub>CEx</sub>	—	-50	nA	V <sub>CE</sub> = -30V, V <sub>EB(OFF)</sub> = -0.5V
Base Cutoff Current	I <sub>BL</sub>	—	-50	nA	V <sub>CE</sub> = -30V, V <sub>EB(OFF)</sub> = -0.5V
<b>ON CHARACTERISTICS (Note 10)</b>					
DC Current Gain	h <sub>FE</sub>	75 100 100 100 50	— — — 300 —	—	I <sub>C</sub> = -100μA, V <sub>CE</sub> = -10V I <sub>C</sub> = -1.0mA, V <sub>CE</sub> = -10V I <sub>C</sub> = -10mA, V <sub>CE</sub> = -10V I <sub>C</sub> = -150mA, V <sub>CE</sub> = -10V I <sub>C</sub> = -500mA, V <sub>CE</sub> = -10V
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	-0.4 -1.6	V	I <sub>C</sub> = -150mA, I <sub>B</sub> = -15mA I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	—	-1.3 -2.6	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	C <sub>obo</sub>	—	8.0	pF	V <sub>CB</sub> = -10V, f = 1.0MHz, I <sub>E</sub> = 0
Input Capacitance	C <sub>ibo</sub>	—	30	pF	V <sub>EB</sub> = -2.0V, f = 1.0MHz, I <sub>C</sub> = 0
Current Gain-Bandwidth Product	f <sub>T</sub>	200	—	MHz	V <sub>CE</sub> = -20V, I <sub>C</sub> = -50mA, f = 100MHz
<b>SWITCHING CHARACTERISTICS</b>					
Turn-On Time	t <sub>ON</sub>	—	45	ns	—
Delay Time	t <sub>D</sub>	—	10	ns	V <sub>CC</sub> = -30V, I <sub>C</sub> = -150mA,
Rise Time	t <sub>R</sub>	—	40	ns	I <sub>B1</sub> = -15mA
Turn-Off Time	t <sub>OFF</sub>	—	100	ns	—
Storage Time	t <sub>S</sub>	—	80	ns	V <sub>CC</sub> = -6.0V, I <sub>C</sub> = -150mA,
Fall Time	t <sub>F</sub>	—	30	ns	I <sub>B1</sub> = -I <sub>B2</sub> = -15mA

Notes: 10. Short duration pulse test used to minimize self-heating effect.

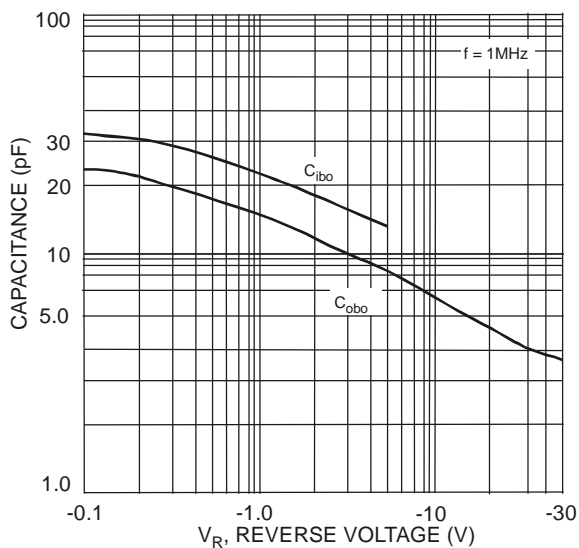


Fig. 3 (2907A) Typical Capacitance

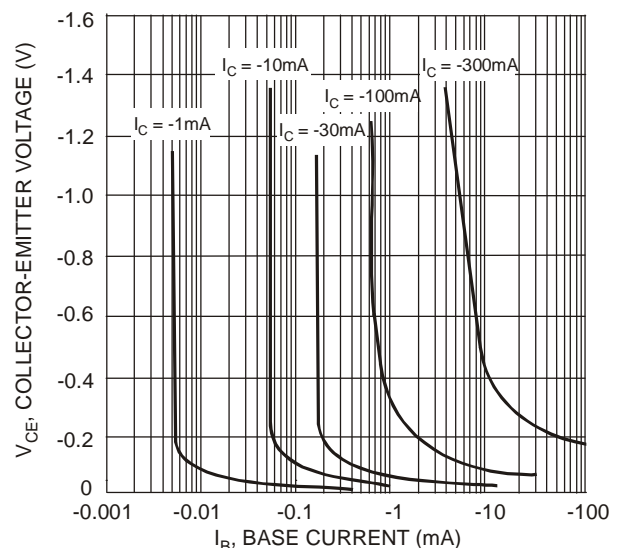
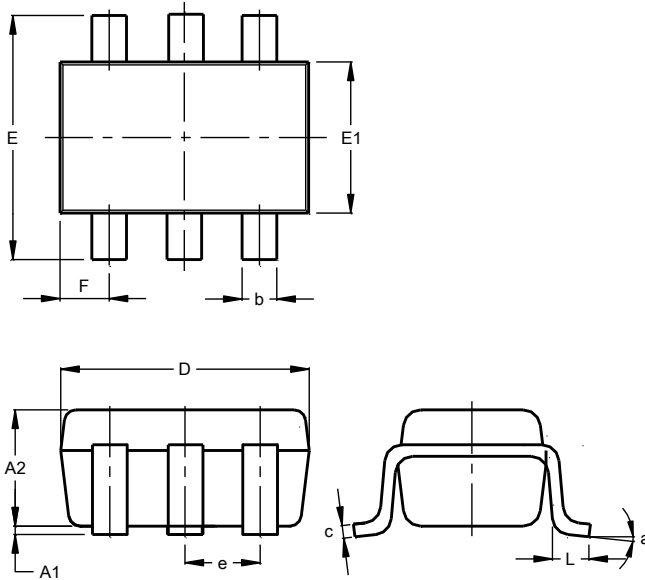


Fig. 4 Typical Collector Saturation Region (2907A Type - PNP)

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT363**

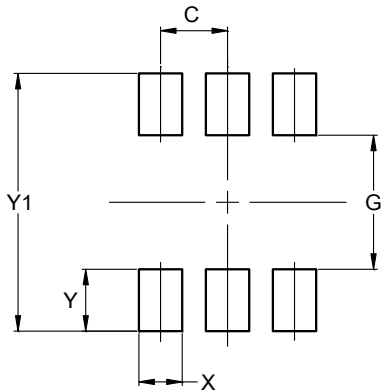


SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT363**



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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